



US0D1008210S

(12)

United States Design Patent

Lee et al.

(10)

Patent No.:

US D1,008,210 S

(45)

Date of Patent:

** Dec. 19, 2023

(54) HEADPHONE

FOREIGN PATENT DOCUMENTS

(71) Applicant: Harman International Industries, Incorporated, Northridge, CA (US)

GB 6216658 * 6/2022

(72) Inventors: Pohsun Lee, Shenzhen (CN); Laurent Lindemberger, Shenzhen (CN)

OTHER PUBLICATIONS

Design U.S. Appl. No. 29/804,308, filed Aug. 19, 2021.
Design U.S. Appl. No. 29/821,531, filed Dec. 30, 2021.

(73) Assignee: Harman International Industries, Incorporated, Northridge, CA (US)

Primary Examiner — Paula Allen Greene
(74) Attorney, Agent, or Firm — Plumsea Law Group, LLC

(**) Term: 15 Years

(21) Appl. No.: 29/803,538

(22) Filed: Aug. 13, 2021

(51) LOC (14) Cl. 14-01

(52) U.S. Cl. USPC D14/223

(58) Field of Classification Search
USPC D14/223, 205; D24/174; 128/864–866; 381/380–381
CPC H04R 1/10; H04R 25/00; H04R 25/02; H04R 1/1066; H04R 1/1016; H04R 5/0335; H04R 1/02; H04R 9/06; H04R 1/1058; A61F 11/08
See application file for complete search history.

(57) CLAIM

The ornamental design for a headphone, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a headphone showing the new design in a first embodiment;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a rear elevational view thereof;
FIG. 4 is a side elevational view thereof;
FIG. 5 is an opposite side elevational view thereof;
FIG. 6 is a top view thereof;
FIG. 7 is a bottom view thereof;
FIG. 8 is a perspective view of the headphone in a second embodiment, illustrating a mirror image of the headphone of FIGS. 1-7;
FIG. 9 is a front elevational view thereof;
FIG. 10 is a rear elevational view thereof;
FIG. 11 is a side elevational view thereof;
FIG. 12 is an opposite side elevational view thereof;
FIG. 13 is a top view thereof; and
FIG. 14 is a bottom view thereof.
The broken lines immediately adjacent the shaded areas represent the bounds of the claimed design while all other broken lines are directed to environment; the broken lines form no part of the claimed design.

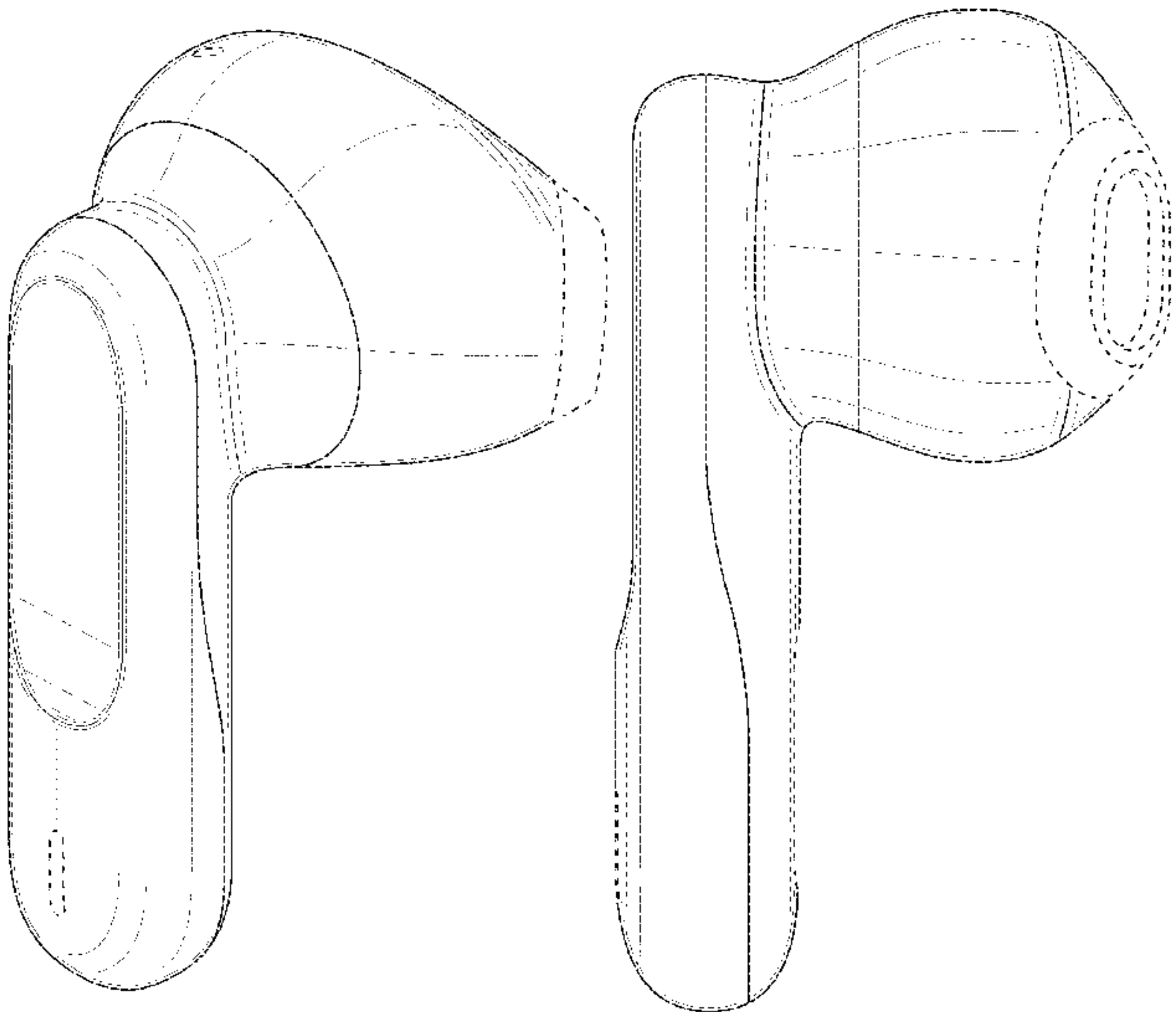
(56) References Cited

U.S. PATENT DOCUMENTS

6,122,369	A *	9/2000	Hwang	H04M 1/6058
				379/430
6,574,345	B1 *	6/2003	Huang	H04R 1/1016
				379/430
6,690,807	B1 *	2/2004	Meyer	G02C 11/06
				381/381
6,731,772	B1 *	5/2004	Byun	H04R 1/12
				181/130
8,345,912	B2 *	1/2013	Akihiko	H04R 1/105
				381/381
8,391,533	B2 *	3/2013	Sim	H04R 1/1041
				381/87
D681,015	S	4/2013	Akana et al.	

(Continued)

1 Claim, 14 Drawing Sheets



(56)

References Cited

U.S. PATENT DOCUMENTS

8,515,116	B2 *	8/2013	Lee	H04R 1/1041 381/373	
D695,718	S	12/2013	Burgett et al.		
D696,230	S	12/2013	Burgett et al.		
D707,206	S	6/2014	Akana et al.		
8,800,712	B2 *	8/2014	Campbell	H04R 25/652 181/135	
D713,385	S	9/2014	Burgett et al.		
8,831,266	B1 *	9/2014	Huang	H04R 1/2826 381/372	
D716,771	S	11/2014	Burgett et al.		
8,965,030	B2 *	2/2015	Aase	H04R 1/1016 381/370	
D725,081	S	3/2015	Burgett et al.		
D725,634	S	3/2015	Burgett et al.		
D725,635	S	3/2015	Burgett et al.		
D732,008	S	6/2015	Akana et al.		
D746,268	S	12/2015	Karayiannis et al.		
D769,849	S	10/2016	Akana et al.		
D801,314	S	10/2017	Akana et al.		
D820,809	S	6/2018	Akana et al.		
10,003,880	B2 *	6/2018	Wagman	H01R 13/521	
D832,232	S	10/2018	Czaniecki et al.		
D847,125	S	4/2019	Akana et al.		
D867,325	S	11/2019	Akana et al.		
D900,065	S	10/2020	Distefano		
D918,182	S *	5/2021	Chen	D14/223	
D920,291	S *	5/2021	Hou	D14/223	
D920,293	S *	5/2021	Chen	D14/223	
D921,615	S *	6/2021	Wu	D14/223	
D922,986	S *	6/2021	Li	D14/223	
D922,987	S *	6/2021	Yoo	D14/223	
D924,209	S *	7/2021	Wu	D14/223	
D924,851	S *	7/2021	Li	D14/223	
D924,852	S *	7/2021	Liu	D14/223	
D925,495	S *	7/2021	Liu	D14/223	
D925,498	S *	7/2021	Lin	D14/223	
D925,499	S *	7/2021	Xie	D14/223	
D925,500	S *	7/2021	Chen	D14/223	
D926,733	S *	8/2021	Wu	D14/223	
D928,126	S *	8/2021	Chen	D14/223	
D929,374	S *	8/2021	Akana	D14/223	
D929,379	S *	8/2021	Woo	D14/223	
D929,380	S *	8/2021	Park	D14/223	
D930,621	S *	9/2021	Rong	D14/223	
D931,255	S *	9/2021	Zhang	D14/223	
D934,839	S *	11/2021	Zhong	D14/223	
D935,446	S *	11/2021	Yi	D14/223	
D936,037	S *	11/2021	Zhou	D14/206	
D938,386	S *	12/2021	Park	D14/205	
D938,387	S *	12/2021	Park	D14/205	
D938,935	S *	12/2021	Park	D14/205	
D940,692	S *	1/2022	Quan	D14/223	
D941,276	S *	1/2022	Levy	D14/223	
D942,425	S *	2/2022	Pi	D14/223	
D943,555	S *	2/2022	Deng	D14/223	
D944,232	S *	2/2022	Yi	D14/223	
D945,402	S *	3/2022	Yu	D14/223	
D946,555	S *	3/2022	Chen	D14/223	
D947,818	S *	4/2022	Zhang	D14/223	
D950,525	S *	5/2022	Chen	D14/223	
D953,300	S *	5/2022	Li	D14/223	
D956,719	S *	7/2022	Huang	D14/223	
D956,722	S *	7/2022	Zhou	D14/223	
D957,367	S *	7/2022	Sun	D14/223	
D967,069	S *	10/2022	Zhu	D14/223	
D967,802	S *	10/2022	Zhang	D14/223	
D967,805	S *	10/2022	Hong	D14/223	
D968,371	S *	11/2022	Ao	D14/223	
D971,183	S *	11/2022	He	D14/223	
D975,063	S *	1/2023	Huang	D14/223	
D977,458	S *	2/2023	Cai	D14/223	
D977,461	S *	2/2023	Lin	D14/223	
D977,462	S *	2/2023	Yi	D14/223	
D981,373	S *	3/2023	Jiang	D14/223	
D984,420	S *	4/2023	Wang	D14/223	
2012/0003937	A1 *	1/2012	Zhong	H04M 1/6066 455/41.3	
2017/0094392	A1	3/2017	Zorkendorfer et al.		
2019/0182575	A1 *	6/2019	Julstrom	H04R 1/086	
2020/0252715	A1 *	8/2020	Zhou	H04R 1/1016	
2022/0001628	A1 *	1/2022	Jansen	A45C 5/02	

* cited by examiner

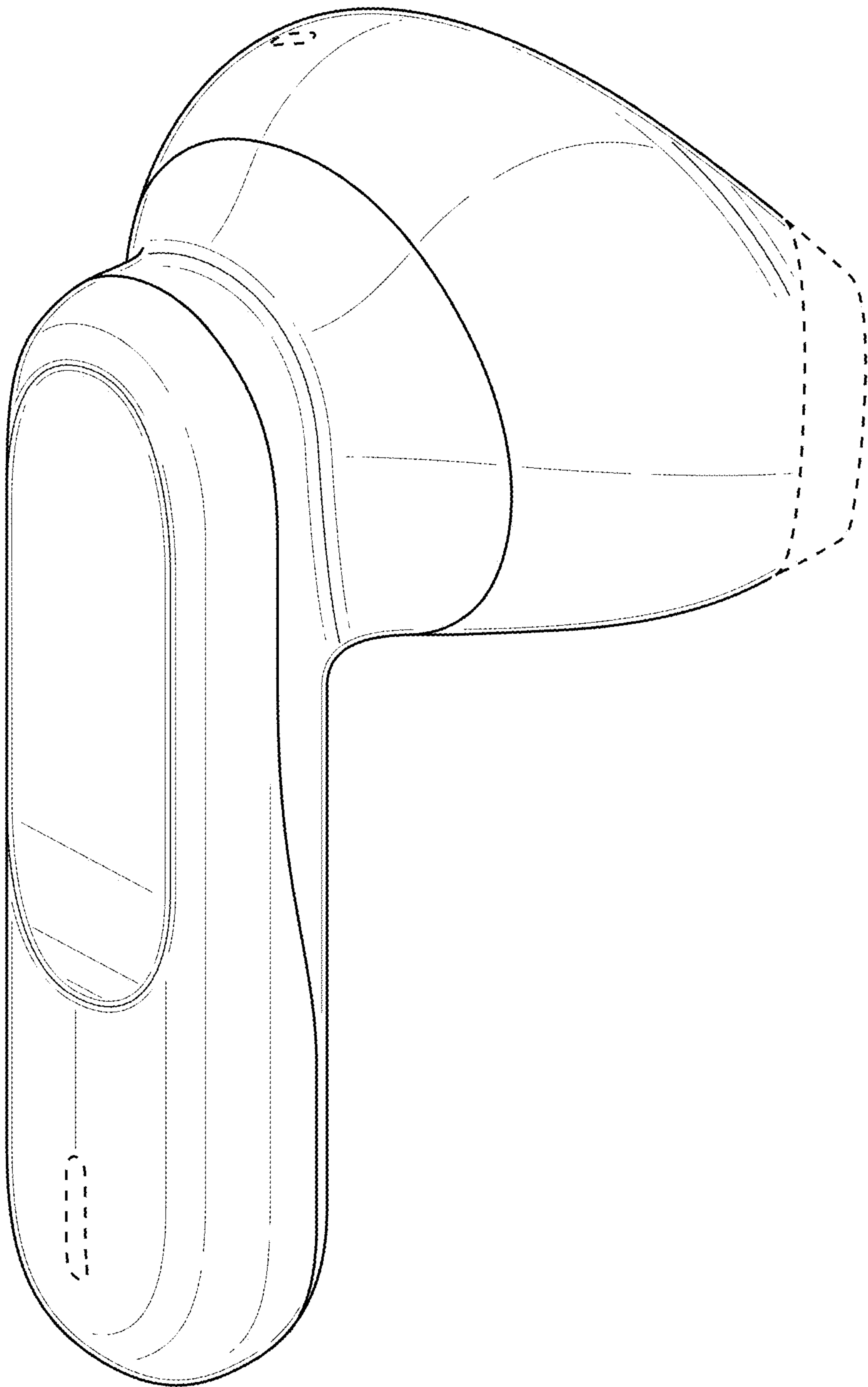


FIG. 1

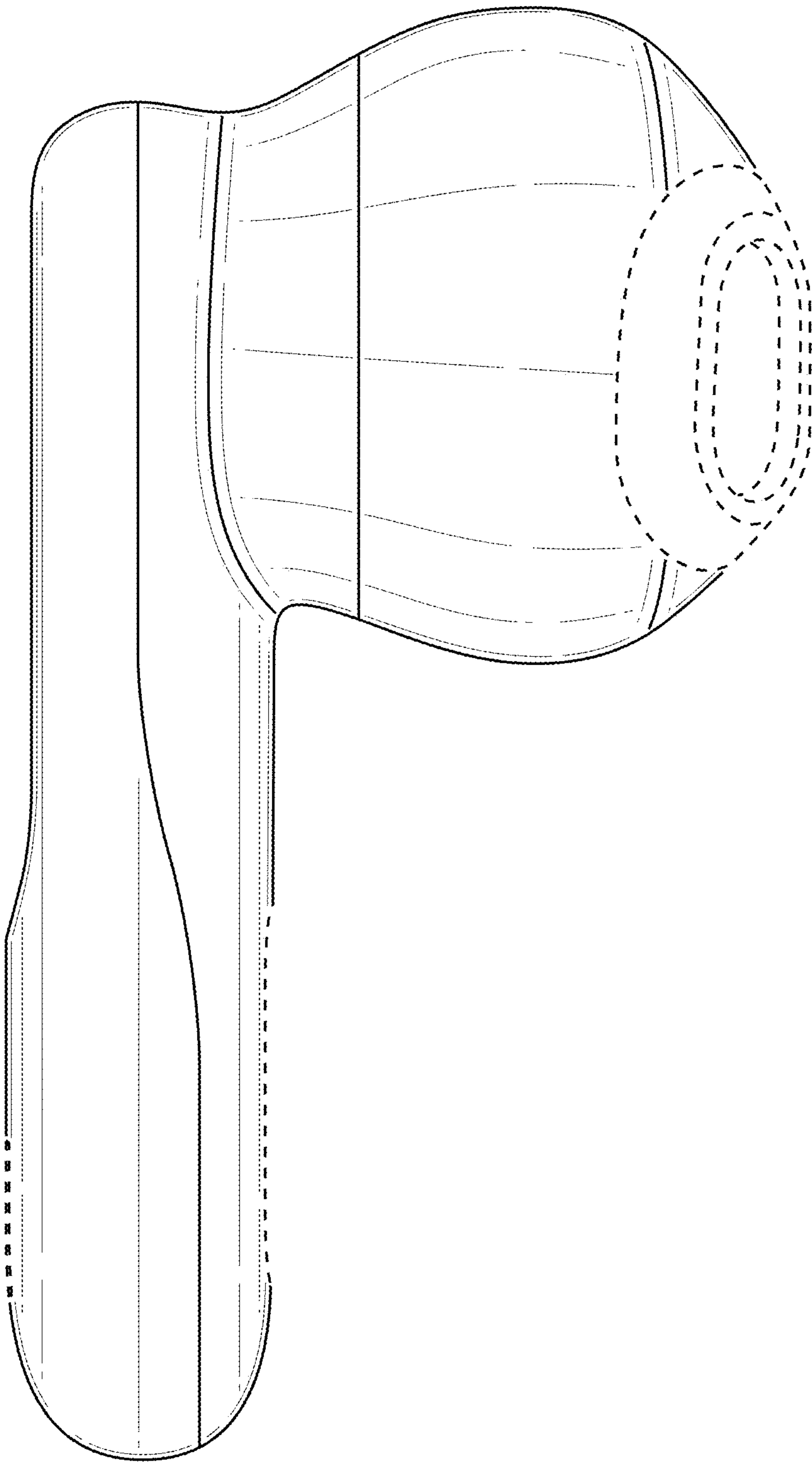


FIG. 2

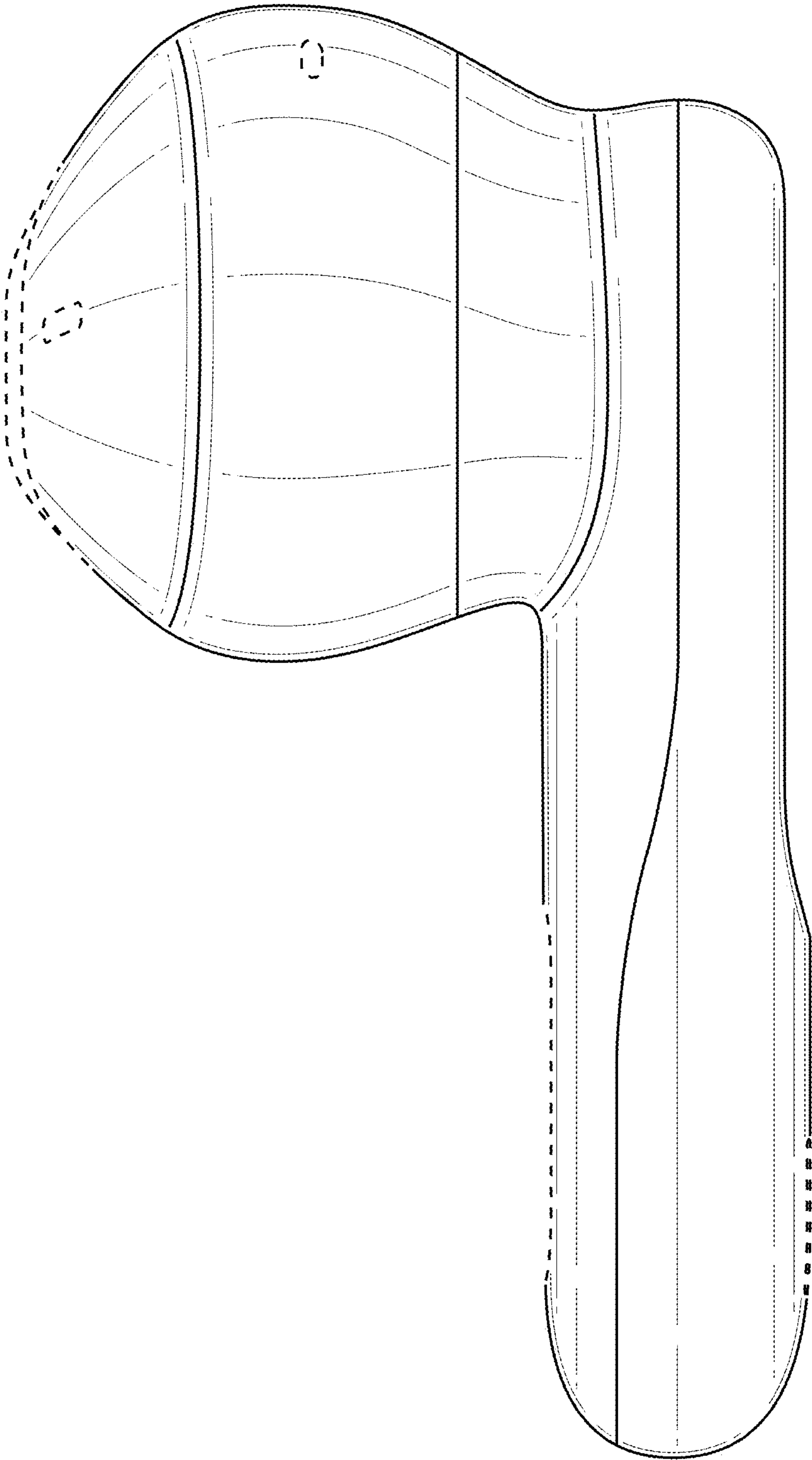


FIG. 3

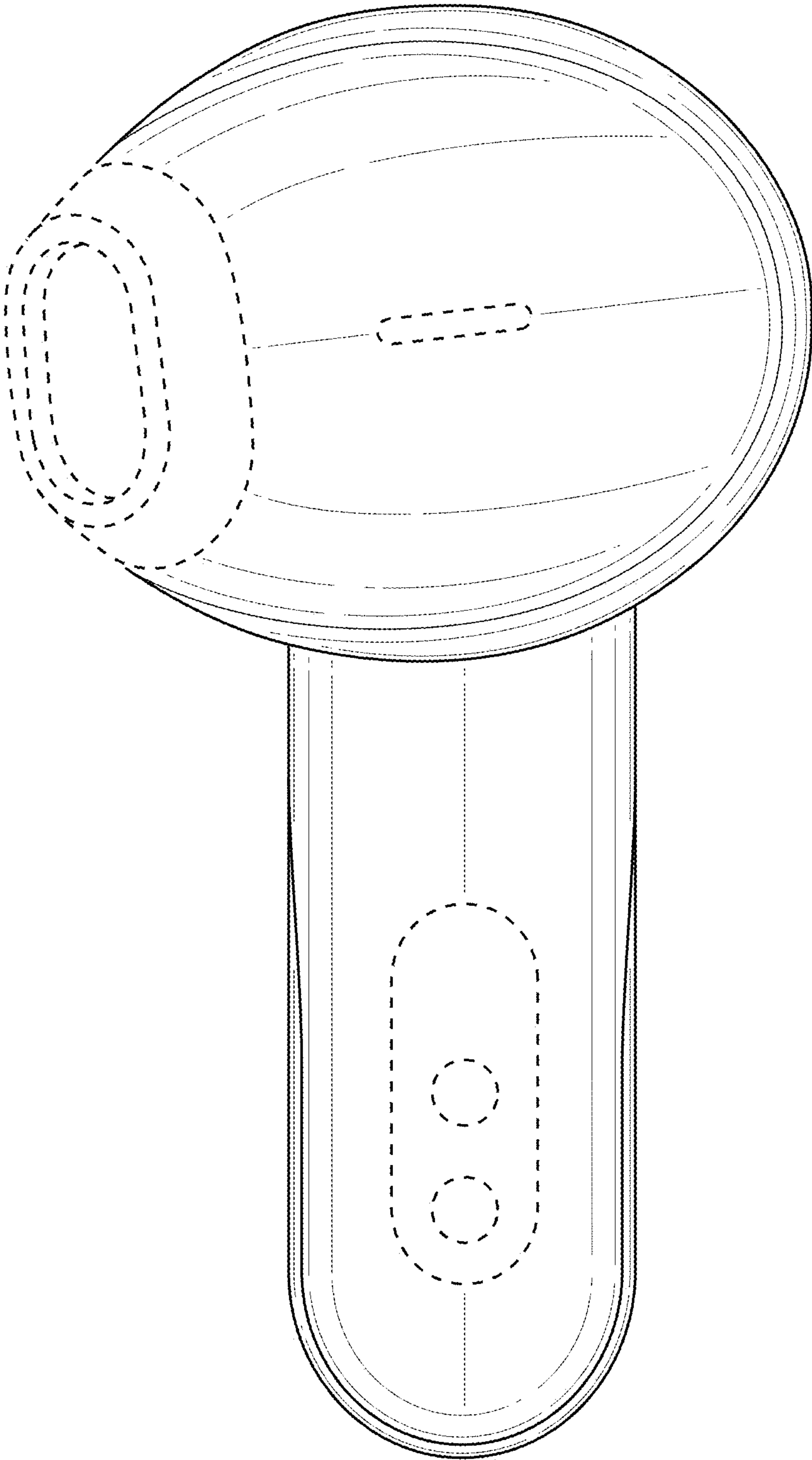


FIG. 4

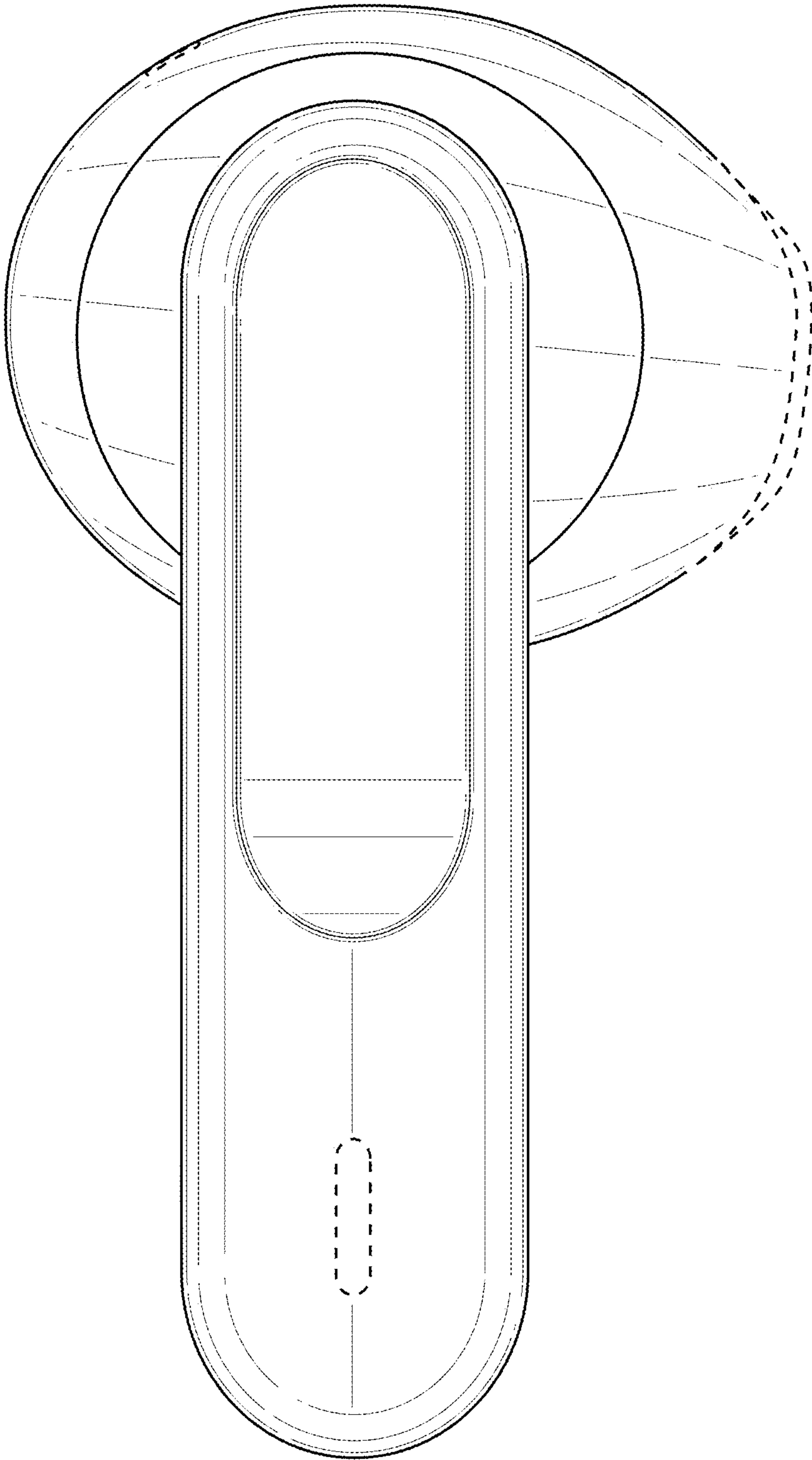


FIG. 5

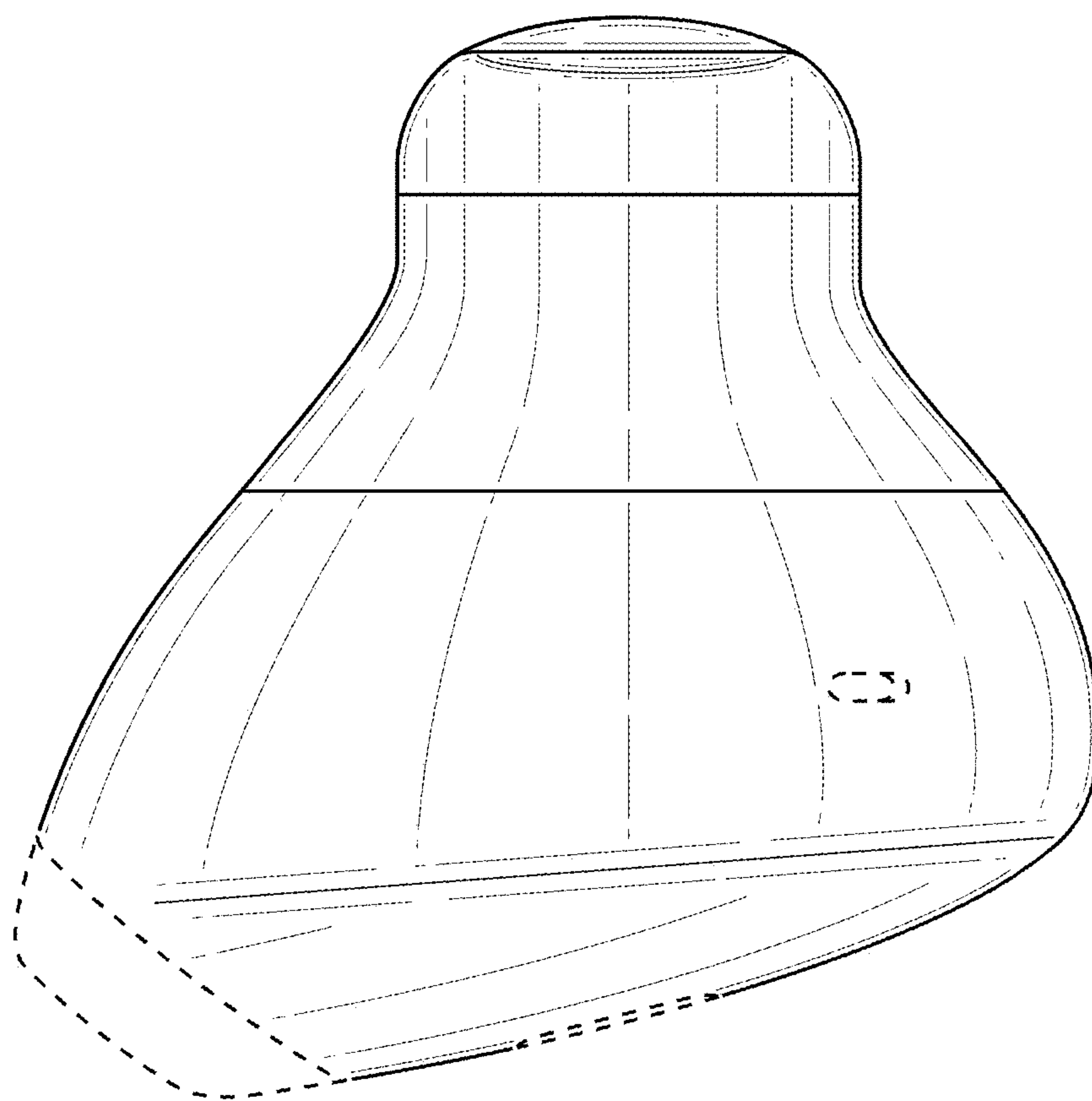


FIG. 6

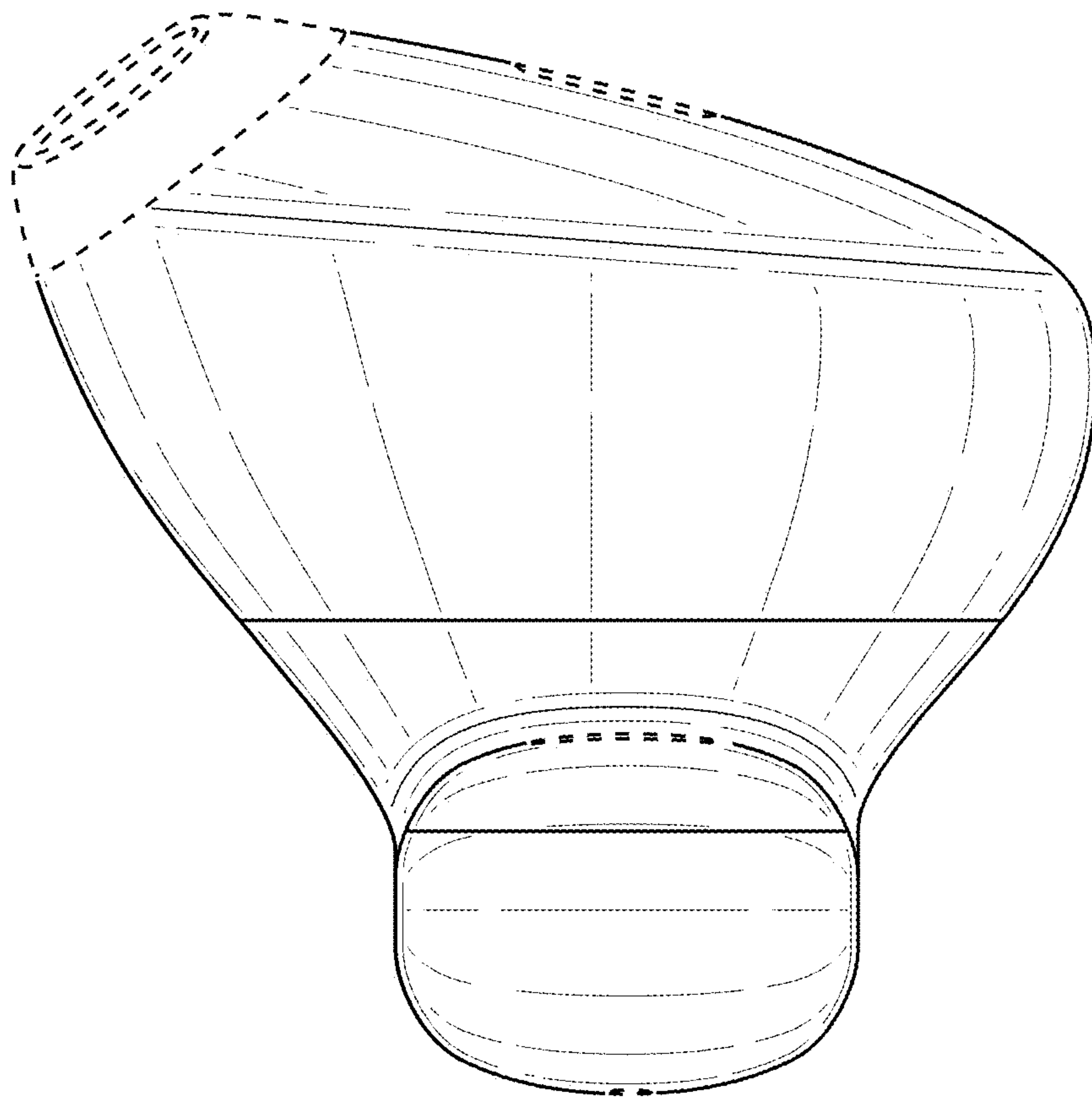


FIG. 7

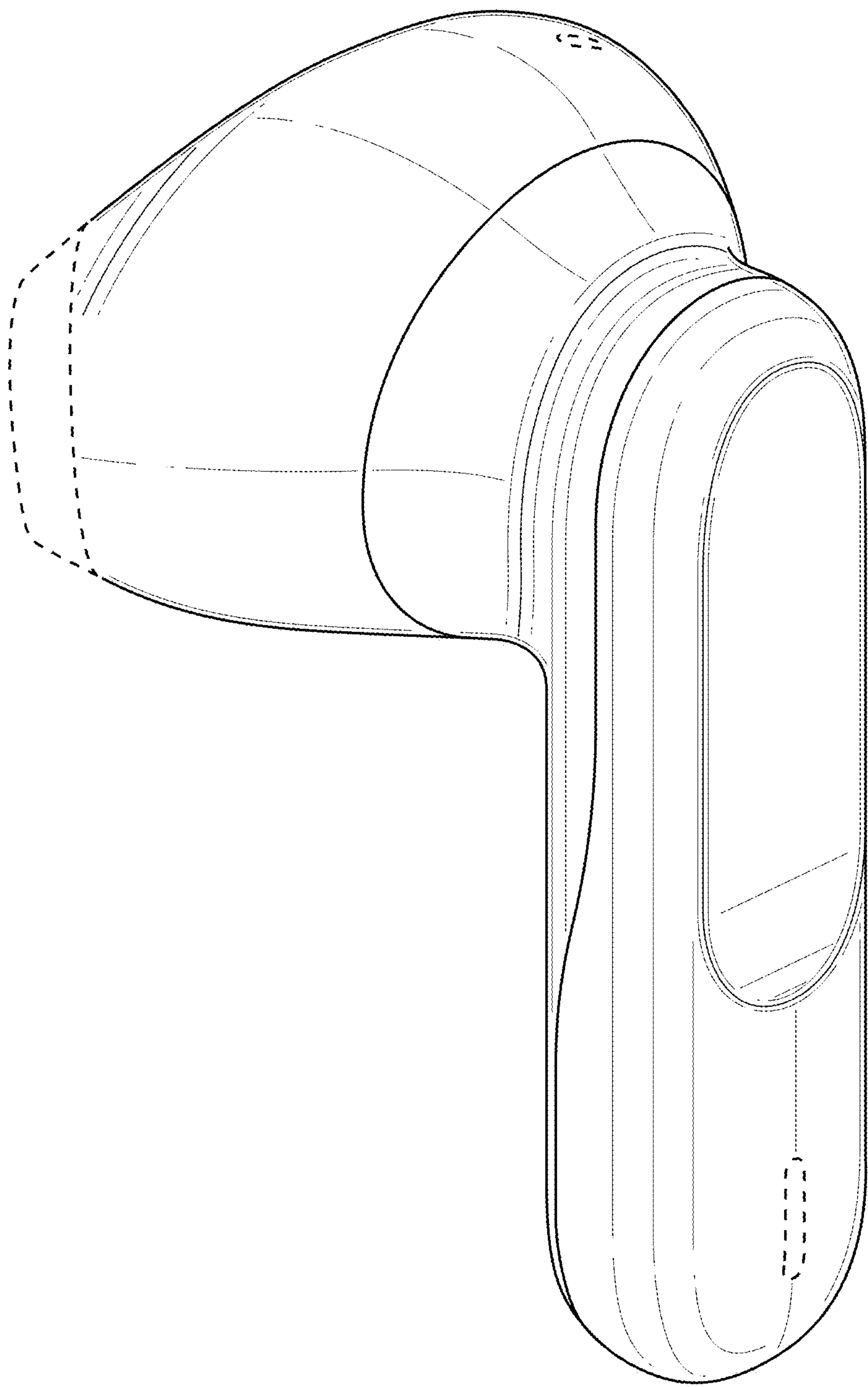


FIG. 8

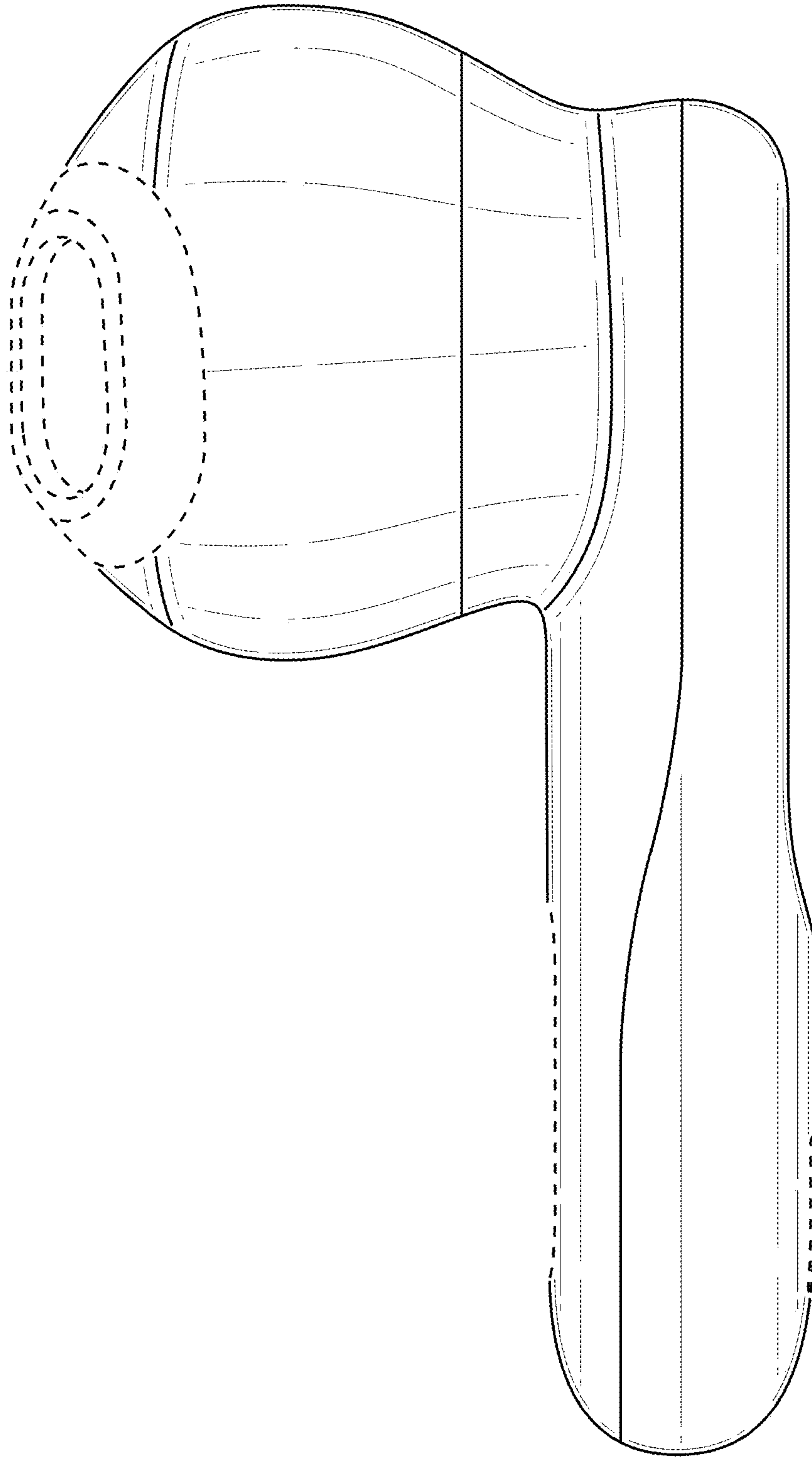


FIG. 9

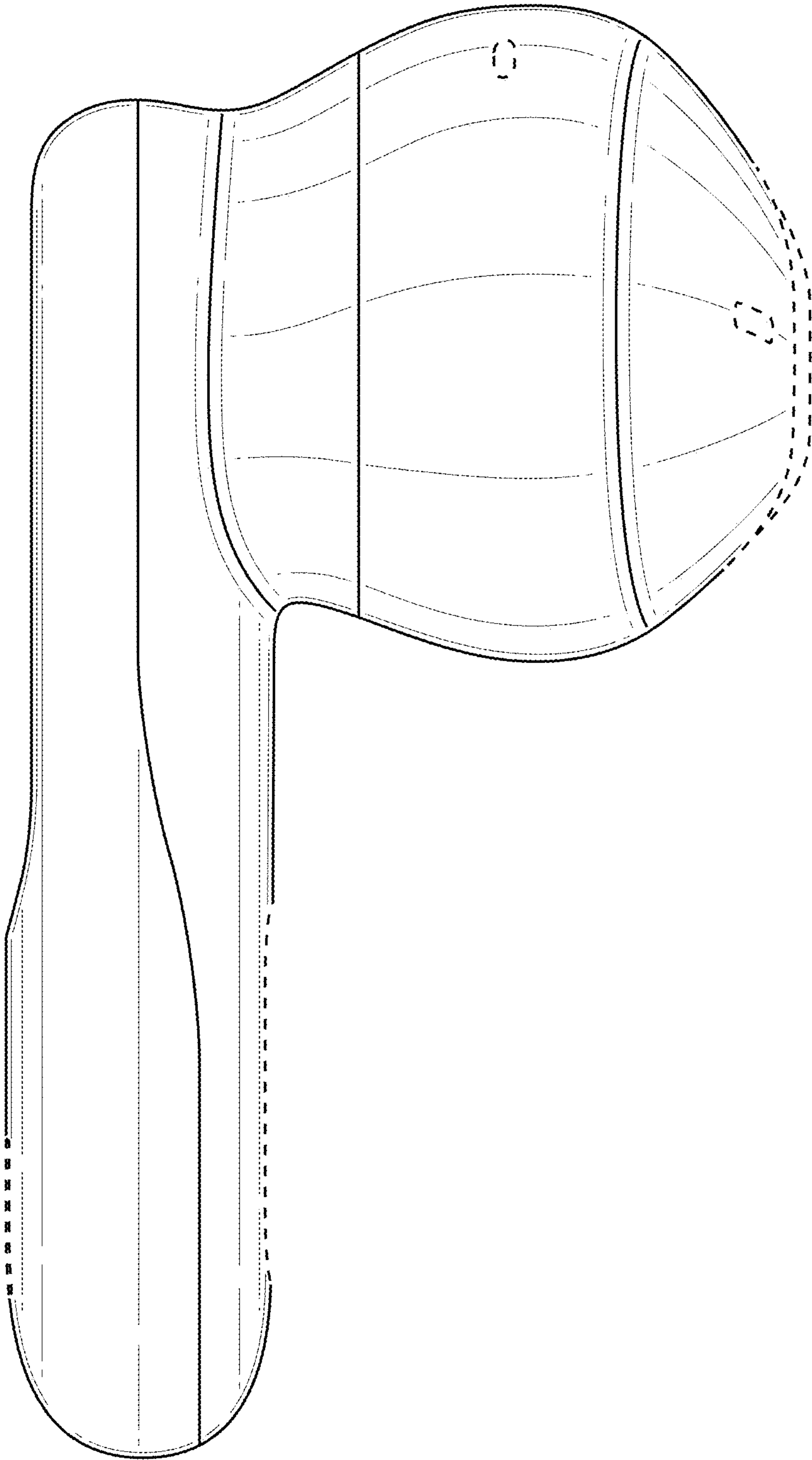


FIG. 10

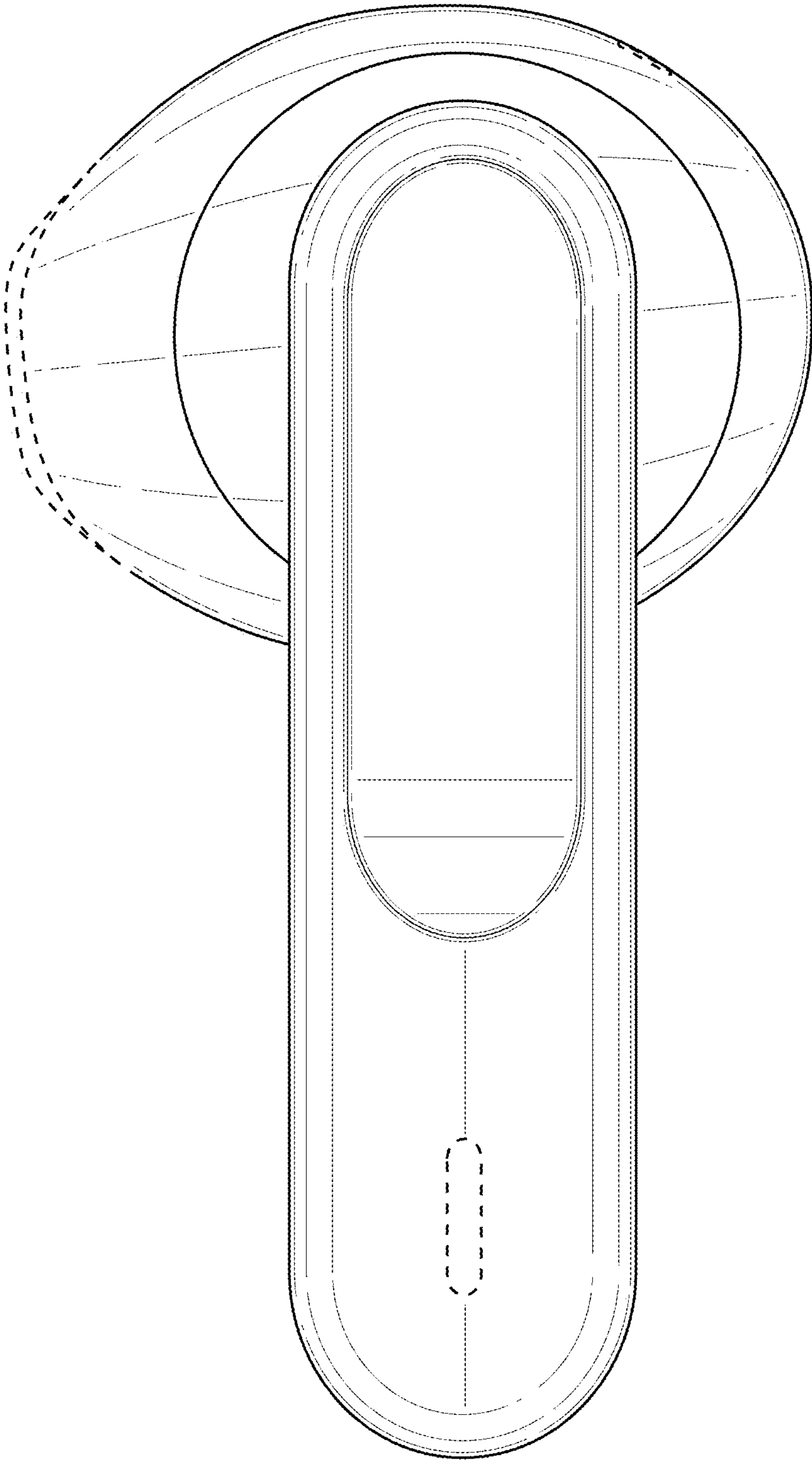


FIG. 11

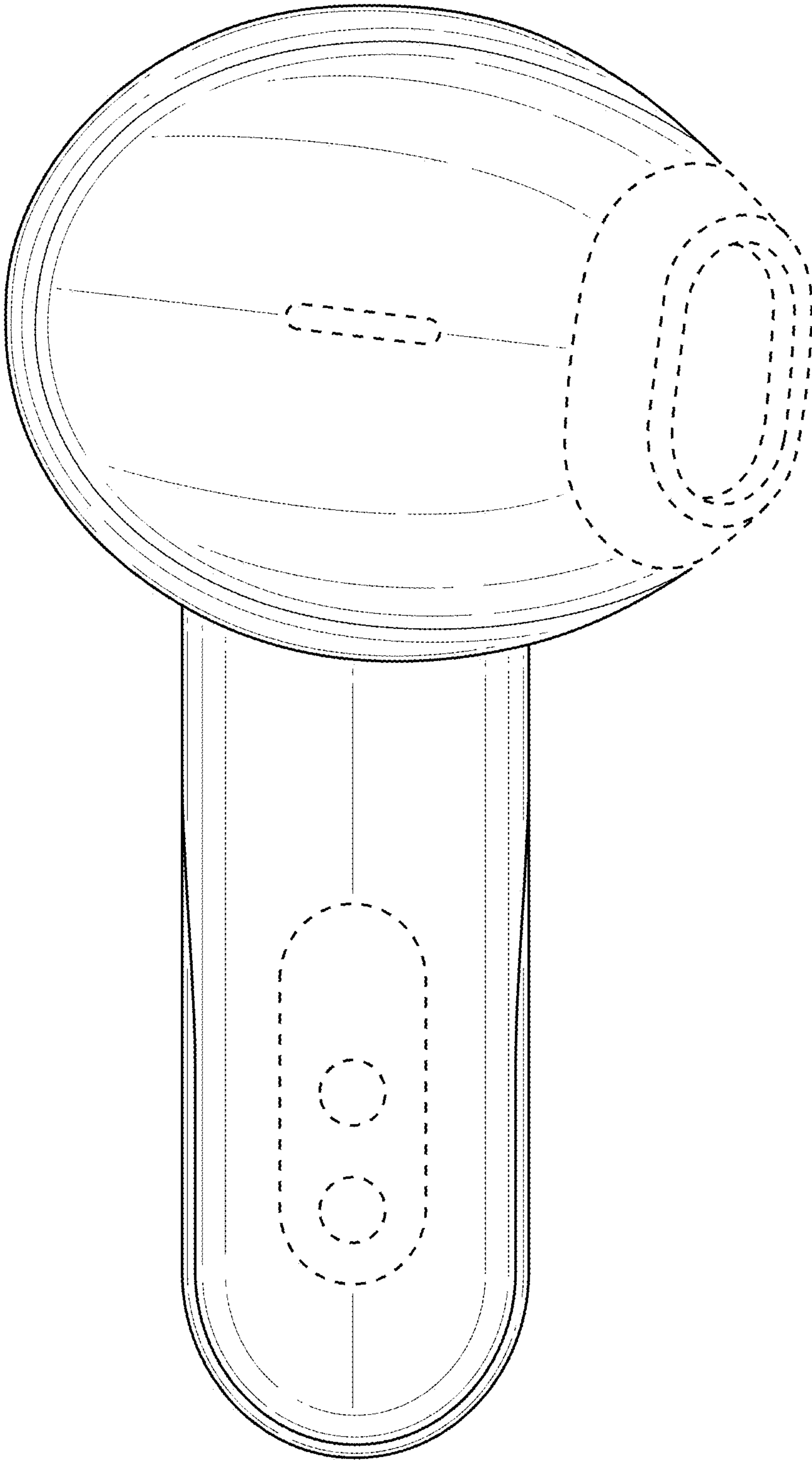


FIG. 12

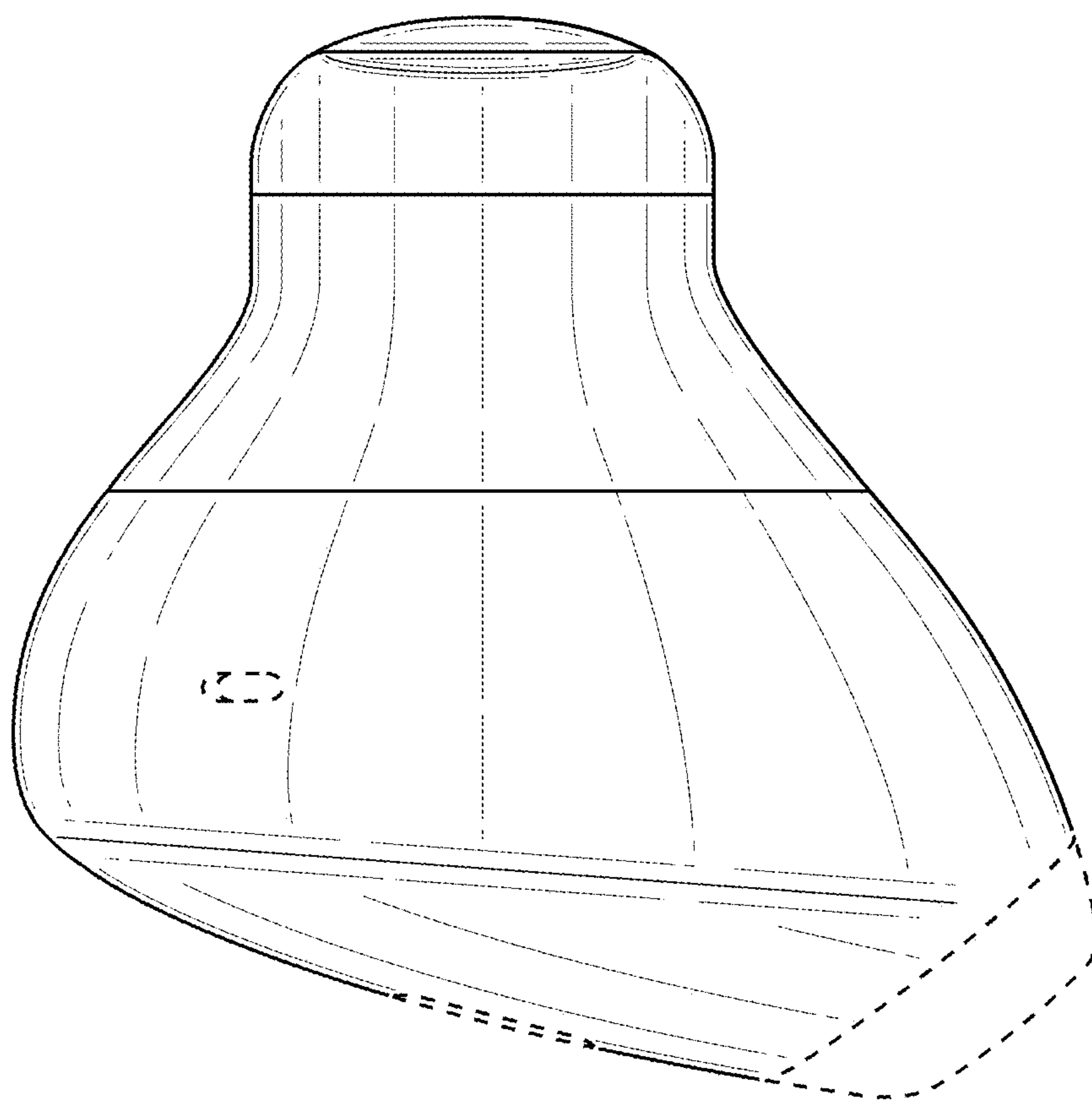


FIG. 13

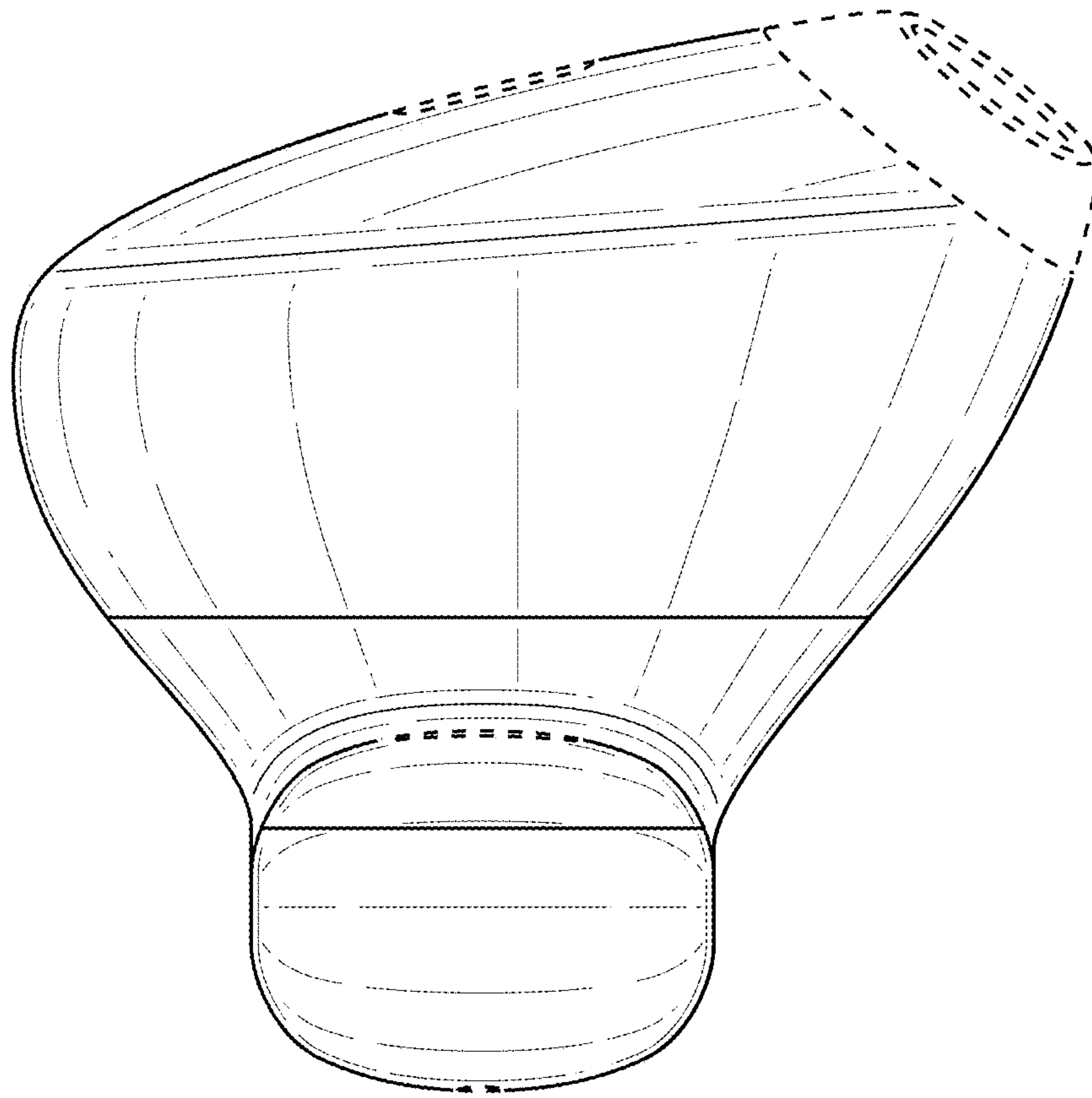


FIG. 14